19 MAR 2002

[Document Name] ABSTRACT

G00002

[Abstract]

[Problems] To provide a compact semiconductor device incorporating a plurality of semiconductor chips at high density and a method of manufacturing the same, of a circuit board and of an electronic instrument.

[Means for Solving the Problems] A semiconductor device comprises a plurality of semiconductor chips 20, 30 having electrodes 22, 32 and aligned in the horizontal direction; a substrate 10 on which is formed an interconnect pattern 12 having bonding portions 14 connected to the electrodes 22, 32 of the semiconductor chips 20, 30 and lands 16 connected to the bonding portions 14, and external electrodes 40 provided on the lands 16 and connected to the electrodes 22, 32 through an interconnect pattern 12.

[Selected Figure] Fig. 1

162162